

## 6089-127 Rev A Heatsink Removal

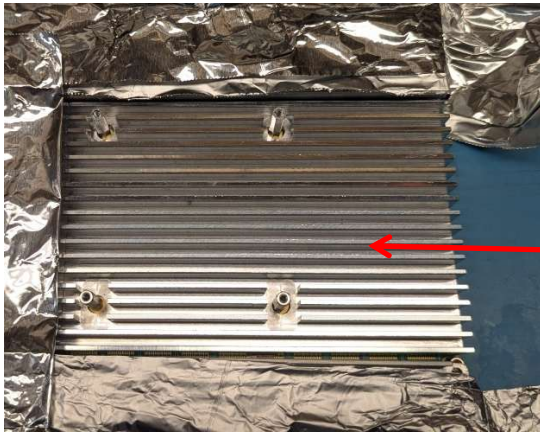
The thermal interface material (TIM) that is used to provide good heat transfer from active devices to their heatsink has the tendency to “glue” the heatsink to the device. The device or the circuit board can be damaged if the heatsink is just pried off with mechanical force. One could possibly pull the lid off the FPGA or pull the FireFly sockets from the board.

Removal requires that the heatsink be slightly warmed, typically to about 60 degC or 150 degF.

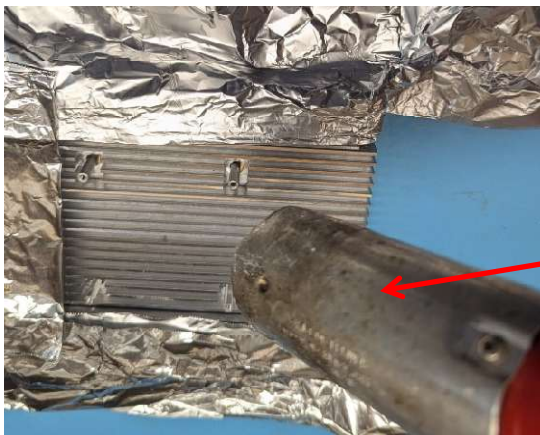
- 1) Remove all retaining screws and springs. It can be useful to remove the FPGA standoffs.
- 2) Mask portions of the board that should not be heated with aluminum foil. This is to prevent inadvertent damage to parts, fibers, or the board.
- 3) Use a hot air gun to uniformly warm the heatsink. Periodically try to move the heatsink. At some point it will slide or lift and can be removed.
- 4) Once the heatsink is removed, clean all residual TIM from the devices and the heatsink.



FireFly Heatsink  
masked with foil



FPGA Heatsink  
masked with foil



Hotair heatgun used  
to warm heatsink